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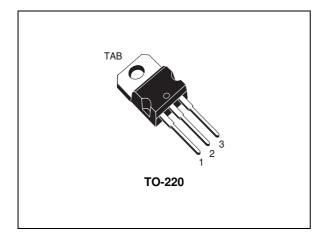




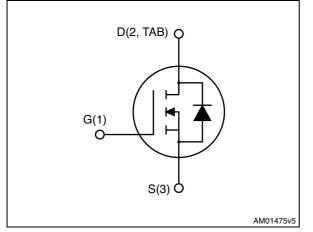
## STP160N4LF6

Datasheet - production data

### N-channel 40 V, 0.0021 mΩ typ., 120 A, STripFET<sup>™</sup> VI DeepGATE<sup>™</sup> Power MOSFET in a TO-220 package



#### Figure 1. Internal schematic diagram



#### Features

Order code	$V_{\text{DS}}$	R <sub>DS(on)</sub> max	I <sub>D</sub>	P <sub>TOT</sub>
STP160N4LF6	40 V	0.0029 Ω	120 A	150 W

- R<sub>DS(on)</sub> \* Q<sub>g</sub> industry benchmark
- Extremely low on-resistance R<sub>DS(on)</sub>
- Logic level drive
- High avalanche ruggedness
- 100% avalanche tested

#### **Applications**

• Switching applications

### Description

This device is an N-channel Power MOSFET developed using the 6<sup>th</sup> generation of STripFET<sup>™</sup> DeepGATE<sup>™</sup> technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest R<sub>DS(on)</sub> in all packages.

#### Table 1. Device summary

Order code	Marking	Package	Packaging
STP160N4LF6	160N4LF6	TO-220	Tube

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This is information on a product in full production.

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## 1 Electrical ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage	40	V
V <sub>GS</sub>	Gate-source voltage	± 20	V
۱ <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	120	А
۱ <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	100	А
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	480	А
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	150	W
	Derating factor	1	W/°C
I <sub>AS</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>jmax</sub> )	60	А
E <sub>AS</sub>	Single pulse avalanche energy	323	mJ
T <sub>stg</sub>	Storage temperature	-55 to 175	°C
Т <sub>ј</sub>	Operating junction temperature	-5510175	C

#### Table 2. Absolute maximum ratings

1. Pulse width is limited by safe operating area

#### Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	1.0	°C/W
R <sub>thj-a</sub>	Thermal resistance junction-ambient max	62.5	°C/W



## 2 Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage (V <sub>GS</sub> = 0)	I <sub>D</sub> = 250 μA	40			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 20 V V <sub>DS</sub> = 20 V, Tc = 125 °C			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1			V
Brach	Static drain-source on-	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 60 \text{ A}$		0.0022	0.0029	Ω
R <sub>DS(on)</sub>	resistance	$V_{GS} = 5 V, I_{D} = 60 A$		0.0024	0.0031	Ω

Table 4. Static

#### Table 5. Dynamic

Symbol	Parameter	Test conditions	Min	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance		-	8130	-	pF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 20 V, f=1 MHz,	-	770	-	pF
C <sub>rss</sub>	Reverse transfer capacitance	V <sub>GS</sub> = 0 V	-	670	-	pF
Qg	Total gate charge	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 60 A	-	181	-	nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 10 V	-	22	-	nC
Q <sub>gd</sub>	Gate-drain charge	(see Figure 14)	-	46	-	nC

#### Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time		-	20	-	ns
t <sub>r</sub>	Rise time	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 60 A, R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V	-	131	-	ns
t <sub>d(off)</sub>	Turn-off delay time	(see Figure 15)	-	205	-	ns
t <sub>f</sub>	Fall time		-	116		ns



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		120	А
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		480	А
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	$I_{SD} = 120 \text{ A}, V_{GS} = 0$	-		0.97	V
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 120 A,	-	57		ns
Q <sub>rr</sub>	Reverse recovery charge	di/dt = 100 A/ $\mu$ s,	-	53		nC
I <sub>RRM</sub>	Reverse recovery current	V <sub>DD</sub> = 32 V (see Figure 17)	-	1.86		А

Table 7. Source drain diode

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300  $\mu$ s, duty cycle 1.5%



80DPI

#### **Electrical characteristics (curves)** 2.1

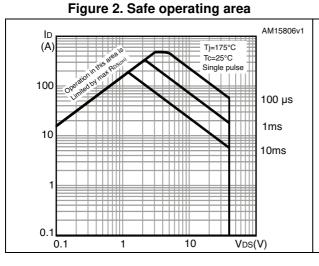


Figure 4. Output characteristics

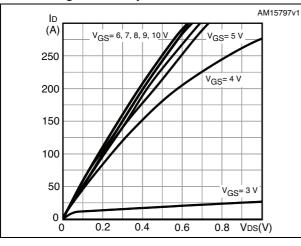
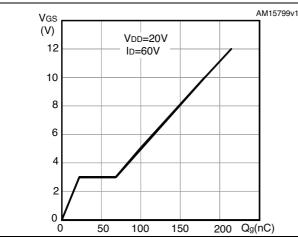


Figure 6. Gate charge vs gate-source voltage



10 -2 10-5 10<sup>-4</sup> 10<sup>-3</sup> 10-2 10<sup>-1</sup> + p (s)

0.05

0.01

∄0.02|

SINGLE PULSE

-----

 $Z_{th} = k R_{thJ-c}$ 

 $\delta=\,{\rm t_p}/\tau$ 

Figure 3. Thermal impedance

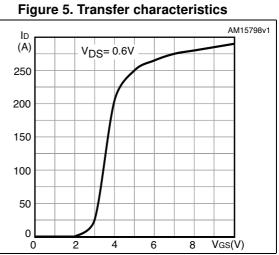
κ

10 -1

 $\delta = 0.5$ 

0.2

0.1





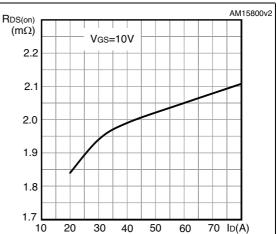
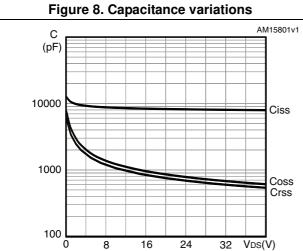
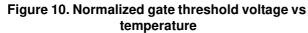


Figure 7. Static drain-source on-resistance

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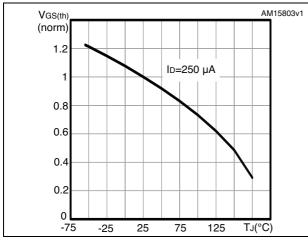


Figure 12. Source-drain diode forward characteristics

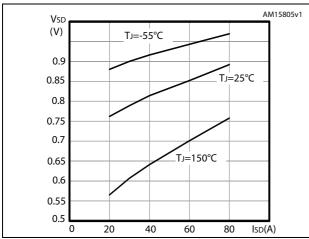


Figure 9. Normalized V<sub>(BR)DSS</sub> vs temperature

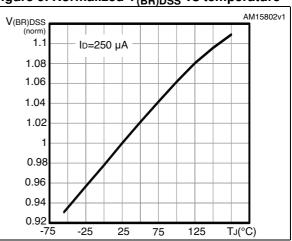
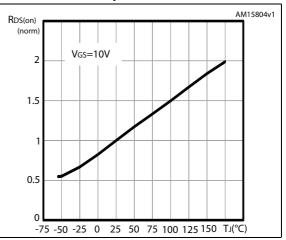


Figure 11. Normalized on-resistance vs temperature





**Electrical characteristics** 

### 3 Test circuits

Figure 13. Switching times test circuit for resistive load

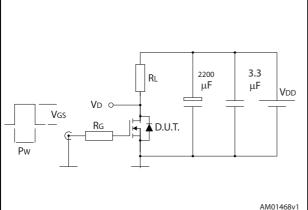


Figure 15. Test circuit for inductive load switching and diode recovery times

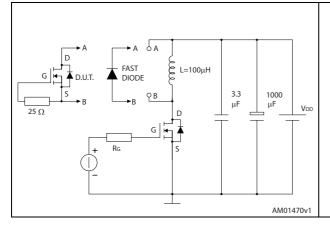


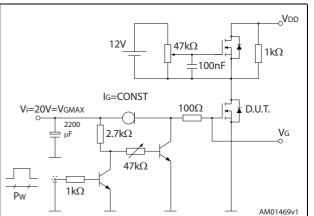
Figure 17. Unclamped inductive waveform

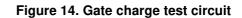
VD

IDM

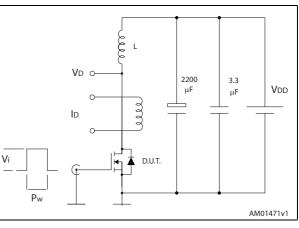
lр

V(BR)DSS









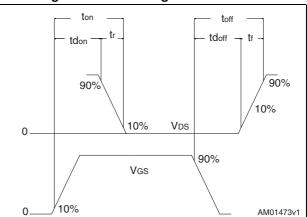


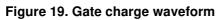
Figure 18. Switching time waveform

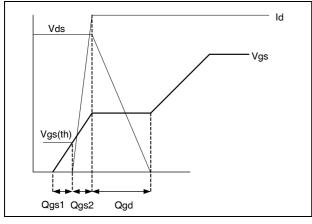
Vdd

AM01472v1



Vdd





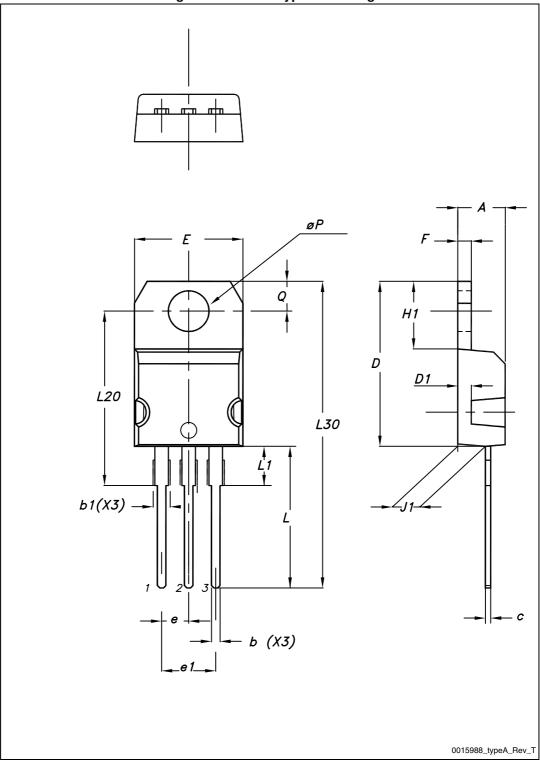


## 4 Package mechanical data

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Figure 20. TO-220 type A drawing



Dim		mm	
Dim. —	Min.	Тур.	Max.
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
с	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Table 8. TO-220 type A mechanical data



## 5 Revision history

Date	Revision	Changes
24-Apr-2014	1	First release.



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